Schottky Barrier Diode Silicon Epitaxial

CBS10S40

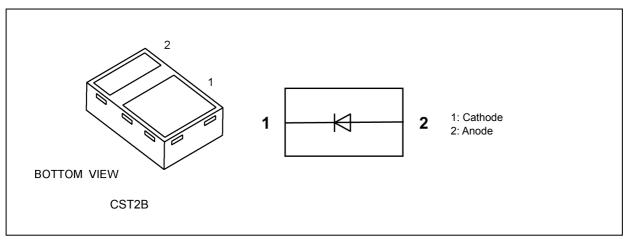
1. Applications

• High-Speed Switching

2. Features

- (1) Low forward voltage: $V_{F(2)} = 0.48 \text{ V}$ (typ.)
- (2) Thin and compact packaging: Height = 0.40mm(max)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25^{\circ}C$)

Characteristics	Symbol	Note	Rating	Unit
Peak reverse voltage	V _{RM}	_	40	V
Reverse voltage	V _R	—	30	
Average rectified current	Ι _Ο	(Note 1)	1.0	А
Non-repetitive peak forward surge current	I _{FSM}	(Note 2)	3	
Junction temperature	Тj	_	125	°C
Storage temperature	T _{stg}	_	-55 to 125	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on an FR4 board.

(25.4 mm \times 25.4 mm \times 1.6 mm, Cu Pad: 645 mm²)

Note 2: Measured with a 10 ms pulse.

5. Electrical Characteristics (Unless otherwise specified, $T_a = 25^{\circ}C$)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V _{F(1)}	I _F = 0.5 A (pulse test)	_	0.36	0.40	V
	V _{F(2)}	I _F = 1 A (pulse test)	_	0.48	0.55	
Reverse current	I _R	V _R = 40 V (pulse test)	_	_	150	μA
Total capacitance	Ct	V _R = 0 V, f = 1 MHz	_	120		pF

6. Marking

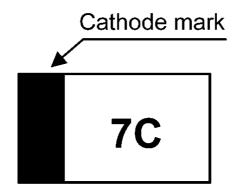


Fig. 6.1 Marking

Marking Code	Part Number	
7C	CBS10S40	

7. Usage Considerations

• Schottky barrier diodes (SBDs) have reverse leakage greater than other types of diodes. This makes SBDs more susceptible to thermal runaway under high-temperature and high-voltage conditions. Thus, both forward and reverse power losses of SBDs should be considered for thermal and safety design.

8. Land pattern dimensions for reference only

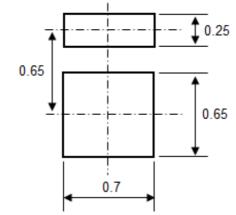


Fig. 8.1 Land pattern dimensions for reference only (Unit: mm)

°C

50°C

25°C

Ta = -25 °C

30

40

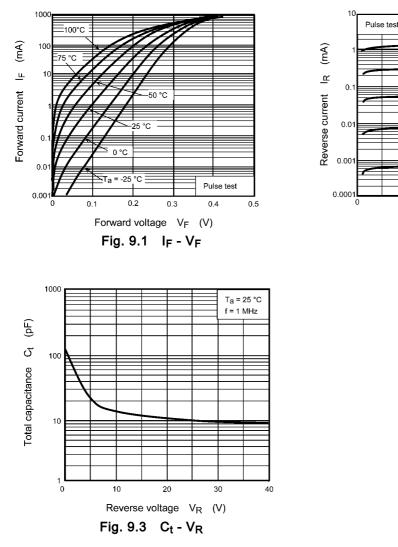
20

Reverse voltage V_R (V)

Fig. 9.2 I_R - V_R

10

9. Characteristics Curves (Note)



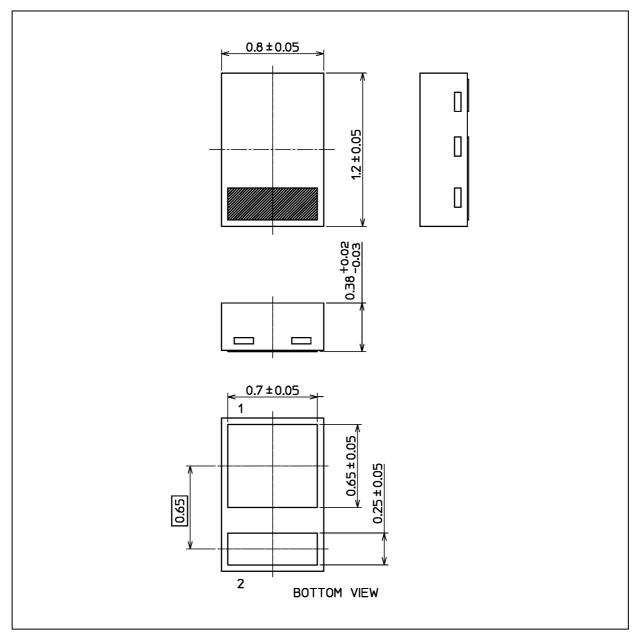
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



CBS10S40

Package Dimensions

Unit: mm





	Package Name(s)
Nickname: CST2B	

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